Product Change Notification

108194 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108194 - 00

Change Title: Intel® High Speed PHY Products, PCN 108194-00, Product Material, Change in Mold Compound and Bonding Wire

Date of Publication: January 04, 2008

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 10, 2008

Description of Change to the Customer:

In order to ensure a continuous supply of the products listed in the Products Affected table below, Intel Corporation has changed two sub-components for the LXT16726 and LXT16727 packages:

1). mold compound supplier

2). bonding wire has changed from AW 88 to AW 66

Customer Impact of Change and Recommended Action:

Intel is in process of final qualification of the mold compound package component. Normal product production will resume upon completion of the mold compound qualification. We anticipate returning to normal delivery and lead times in February 2008.

There is no form, fit or function change to Intel® LXT16726 or Intel®LXT16727 caused by the two changes.

Products Affected / Intel Ordering Codes:

Affected Product Code	Affected S-Spec	Affected MM#
RCLXT16727FE		853645
RCLXT16726FE		853646
RCLXT16727JA		855168
RCLXT16726JA		855216
RCLXT16727FEA	S L 79Q	857191
PCLXT16726FE	Q 283	875184
PCLXT16727FE	Q 316	875187
PCLXT16727JA	Q 314	875214
PCLXT16727FEA	Q 284	875215
PCLXT16726FE		875482
PCLXT16727FE		875484
PCLXT16727JA		875485
PCLXT16727FEA		875573
PCLXT16726JA		876810

Reference Documents / Attachments:

Document: **Location #:**

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
January 4, 2008	00	Originally Published PCN